

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC032N04LS	**Issued**	1. September 2019
MA#	MA005345383		
Package	PG-TDSON-8-51	**Weight***	101.59 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.447	0.44	0.44	4404	4404
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		134	
	non noble metal	zinc	7440-66-6	0.055	0.05		537	
	non noble metal	iron	7439-89-6	1.090	1.07		10733	
	non noble metal	copper	7440-50-8	44.271	43.60	44.73	435793	447197
wire	noble metal	gold	7440-57-5	0.032	0.03	0.03	313	313
encapsulation	organic material	carbon black	1333-86-4	0.088	0.09		870	
	plastics	epoxy resin	-	4.068	4.00		40039	
	inorganic material	silicondioxide	60676-86-0	40.056	39.43	43.52	394301	435210
leadfinish	non noble metal	tin	7440-31-5	1.264	1.24	1.24	12440	12440
plating	noble metal	silver	7440-22-4	0.029	0.03	0.03	286	286
solder	noble metal	silver	7440-22-4	0.017	0.02		168	
	non noble metal	tin	7440-31-5	0.034	0.03		336	
	non noble metal	lead	7439-92-1	0.631	0.62	0.67	6209	6713
heat sink clip	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	zinc	7440-66-6	0.011	0.01		112	
	non noble metal	iron	7439-89-6	0.228	0.22		2242	
	non noble metal	copper	7440-50-8	9.250	9.11	9.34	91055	93437
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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